AUTOMOTIVI GRADE

RoHS

COMPLIANT

HALOGEN FREE



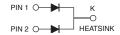
Vishay General Semiconductor

High Current Density Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low $V_F = 0.58 \text{ V}$ at $I_F = 5 \text{ A}$







LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I _{F(AV)}	2 x 20 A			
V _{RRM}	200 V			
I _{FSM}	240 A			
V _F at I _F = 20 A (T _J = 125 °C)	0.75 V			
T _J max.	175 °C			
Package	SlimDPAK (TO-252AE)			
Circuit configuration	Common cathode			

FEATURES

- Very low profile typical height of 1.3 mm
- Trench MOS Schottky technology
- Ideal for automated placement
- · Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

MECHANICAL DATA

Case: SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3_X - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

("_X" denotes revision code e.g. A, B,....)

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER		SYMBOL	V40PW22C	UNIT
Device marking code			V40PW22C	
Maximum repetitive peak reverse voltage		V_{RRM}	200	V
Maximum average forward rectified current (fig. 1)	per device	I _{F(AV)} (1)	40	А
	per diode	I _{F(AV)} (1)	20	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode		I _{FSM}	240	А
Operating junction temperature range		T _J ⁽²⁾	-40 to +175	°C
Storage temperature range		T _{STG}	-55 to +175	°C

Notes

- (1) With infinite heatsink
- (2) The heat generated must be less than the thermal conductivity from junction to ambient: $dP_D/dT_J < 1/R_{\theta,JA}$



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Maximum instantaneous forward voltage	I _F = 5.0 A	T _J = 25 °C	V _E (1)	0.74	-	V
	I _F = 10 A			0.8	-	
	I _F = 20 A			0.89	0.97	
	$I_F = 5.0 \text{ A}$	T _J = 125 °C	VF ('')	0.58	-	
	I _F = 10 A			0.65	-	
	I _F = 20 A			0.75	0.83	
Reverse current	V _R = 160 V	T _J = 25 °C	I _R ⁽²⁾	0.0007	ı	mA
	v _R = 100 v	T _J = 125 °C		1.5	-	
	V _R = 200 V	T _J = 25 °C		-	0.25	
	v _R = ∠00 v	T _J = 125 °C		3	10	
Typical junction capacitance	4.0 V, 1 MHz		CJ	700	-	pF

Notes

 $^{(1)}$ Pulse test: 300 μs pulse width, 1 % duty cycle

(2) Pulse test: pulse width $\leq 5 \text{ ms}$

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V40PW22C	UNIT	
Typical thermal registeres	R ₀ JA (1)(2)	65	°C/W	
Typical thermal resistance	R _{θJM} ⁽³⁾	1.5		

Notes

- $^{(1)}$ The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$ Free air, mounted on recommended copper pad area, 2 oz., FR4 PCB; thermal resistance $R_{\theta JA}$ junction to ambient
- $^{(3)}$ Mounted on infinite heat sink; thermal resistance $R_{\theta JM}$ junction-to-mount

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
V40PW22C-M3/I	0.20	I	4500	13" diameter plastic tape and reel		
V40PW22CHM3_A/I (1)	0.20	I	4500	13" diameter plastic tape and reel		

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

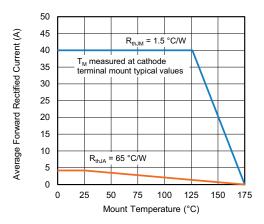


Fig. 1 - Maximum Forward Current Derating Curve

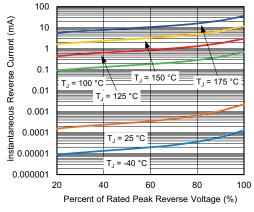


Fig. 4 - Typical Reverse Leakage Characteristics

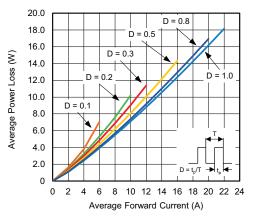


Fig. 2 - Forward Power Loss Characteristics

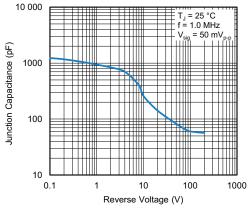


Fig. 5 - Typical Junction Capacitance

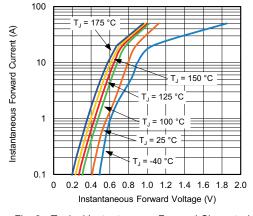


Fig. 3 - Typical Instantaneous Forward Characteristics

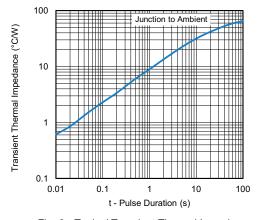


Fig. 6 - Typical Transient Thermal Impedance

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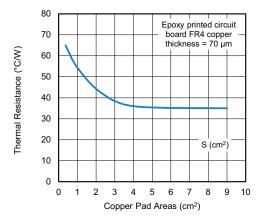
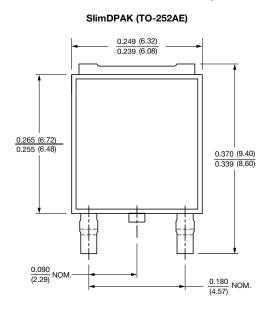


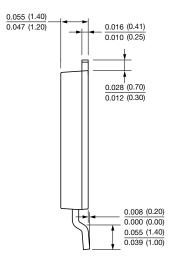
Fig. 7 - Typical Resistance Junction to Ambient vs. Copper Pad Areas



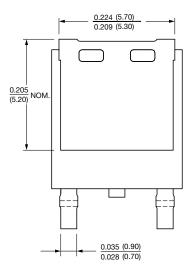
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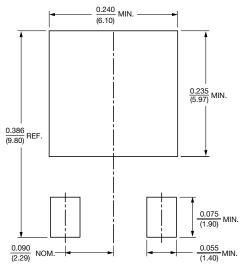
PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





Mounting Pad Layout







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